

	Type	Hits	Search Text
1	IS&R	0	("cleaning same (wafer or substrate) same post same plasma same etching").PN.
2	BRS	28944	(CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE))
3	BRS	598	((POST SAME PLASMA) SAME (ETCH OR ETCHING))
4	BRS	47	"non splash"
5	BRS	3333	(SCRUB\$5 SAME BRUSH)
6	BRS	0	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) same ("NON SPLASH"))
7	BRS	0	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) same ((SCRUB\$5 SAME BRUSH))
8	BRS	0	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) and ("NON SPLASH"))
9	BRS	1	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) AND ((SCRUB\$5 SAME BRUSH))
10	BRS	16	"5174816"
11	BRS	90367	438/\$.ccls.
12	BRS	28942	134/\$.ccls.
13	BRS	14178	216/\$.ccls.
14	BRS	3	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) AND (134/\$.CCLS.))
15	BRS	5	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) AND (216/\$.CCLS.))

	DBs	Time Stamp	C o m m e n t s	E r r o r D e f i n i t i o n	E r r o r s
1	USPAT; JPO; Derwent	2000/07/19 13:56			0
2	USPAT; JPO; Derwent	2000/07/18 13:55			0
3	USPAT; JPO; Derwent	2000/07/18 13:57			0
4	USPAT; JPO; Derwent	2000/07/18 14:00			0
5	USPAT; JPO; Derwent	2000/07/18 14:04			0
6	USPAT; JPO; Derwent	2000/07/18 14:04			0
7	USPAT; JPO; Derwent	2000/07/18 14:04			0
8	USPAT; JPO; Derwent	2000/07/18 14:04			0
9	USPAT; JPO; Derwent	2000/07/18 14:07			0
10	USPAT; JPO; Derwent	2000/07/18 14:07			0
11	USPAT; JPO; Derwent	2000/07/18 15:34			0
12	USPAT; JPO; Derwent	2000/07/18 14:23			0
13	USPAT; JPO; Derwent	2000/07/18 14:24			0
14	USPAT; JPO; Derwent	2000/07/18 14:26			0
15	USPAT; JPO; Derwent	2000/07/18 14:31			0

	Type	Hits	Search Text
16	BRS	16	(((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE)))) AND (438/\$.CCLS.))
17	BRS	42	((((POST SAME PLASMA) SAME (ETCH OR ETCHING))) SAME ((CLEANING SAME (WAFER OR SEMICONDUCTOR OR SUBSTRATE))))
18	BRS	239	438/906.ccls.
19	BRS	625	438/974.ccls.
20	BRS	3045	((ETCH SAME POST) OR (ETCHING SAME POST))
21	BRS	395322	((AME OR (ETCH SAME POST)) OR (ETCHING SAME POST) OR CLEANING)
22	BRS	221	((ETCH SAME POST) OR (ETCHING SAME POST)) SAME CLEANING)
23	BRS	5	((438/906.CCLS.) AND (((ETCH SAME POST) OR (ETCHING SAME POST)) SAME CLEANING)))
24	BRS	3	((438/974.CCLS.) AND (((ETCH SAME POST) OR (ETCHING SAME POST)) SAME CLEANING)))
25	BRS	8	((PLANARIZATION OR SCRUBBING OR POLISHING) SAME "POST CLEANING")
26	BRS	708	438/692
27	BRS	11	((438/692) AND ((SCRUB\$5 SAME BRUSH)))
28	BRS	220	((ETCH SAME Plasma) SAME (DEPOSIT OR RESIDUE)) SAME (REMOVING OR CLEANING OR REMOVAL)
29	BRS	85	((ETCH SAME POST) SAME (DEPOSIT OR RESIDUE)) SAME (REMOVING OR CLEANING OR REMOVAL)
30	BRS	200	(((((ETCH SAME PLASMA) SAME (DEPOSIT OR RESIDUE)) SAME (REMOVING OR CLEANING OR REMOVAL))) NOT (((ETCH SAME POST) SAME (DEPOSIT OR RESIDUE)) SAME (REMOVING OR CLEANING OR REMOVAL))))
31	BRS	269	"brush box"
32	BRS	4	("BRUSH BOX" SAME WAFER SAME CLEANING)
33	BRS	0	("BRUSH BOX" SAME WAFER SAME (plasma adj etching))

	DBs	Time Stamp	C o m m e n t s	E r r o r D e f i n i t i o n	E r r o r s
16	USPAT; JPO; Derwent	2000/07/18 14:41			0
17	USPAT; JPO; Derwent	2000/07/18 15:18			0
18	USPAT; JPO; Derwent	2000/07/18 15:18			0
19	USPAT; JPO; Derwent	2000/07/18 15:19			0
20	USPAT; JPO; Derwent	2000/07/18 15:20			0
21	USPAT; JPO; Derwent	2000/07/18 15:20			0
22	USPAT; JPO; Derwent	2000/07/18 15:21			0
23	USPAT; JPO; Derwent	2000/07/18 15:21			0
24	USPAT; JPO; Derwent	2000/07/18 15:30			0
25	USPAT; JPO; Derwent	2000/07/18 15:31			0
26	USPAT; JPO; Derwent	2000/07/18 15:34			0
27	USPAT; JPO; Derwent	2000/07/18 18:04			0
28	USPAT; JPO; Derwent	2000/07/18 16:30			0
29	USPAT; JPO; Derwent	2000/07/18 16:30			0
30	USPAT; JPO; Derwent	2000/07/18 17:45			0
31	USPAT; JPO; Derwent	2000/07/19 14:13			0
32	USPAT; JPO; Derwent	2000/07/19 14:27			0
33	USPAT; JPO; Derwent	2000/07/19 14:28			0

	Type	Hits	Search Text
34	BRS	0	("BRUSH BOX" SAME WAFER SAME plasma)
35	BRS	2	("ETCH BACK" SAME WEB)
36	BRS	0	("tungsten ETCH BACK" SAME WEB)
37	BRS	1	("TUNGSTEN ETCH BACK" SAME ETCHING SAME PLASMA)

	DBs	Time Stamp	C o m m e n t s	E r r o r D e f i n i t i a l i z a t i o n	E r r o r s
34	USPAT; JPO; Derwent	2000/07/19 14:33			0
35	USPAT; JPO; Derwent	2000/07/19 14:35			0
36	USPAT; JPO; Derwent	2000/07/19 14:35			0
37	USPAT; JPO; Derwent	2000/07/19 14:36			0